

"WAFER BONDING USING REACTIVE FOILS FOR MASSIVELY PARALLEL MICRO-ELECTROMECHANICAL SYSTEMS PACKAGING"

Inventors: Tanya Jegeris Snyder et al.

Docket No.: 10030280-1

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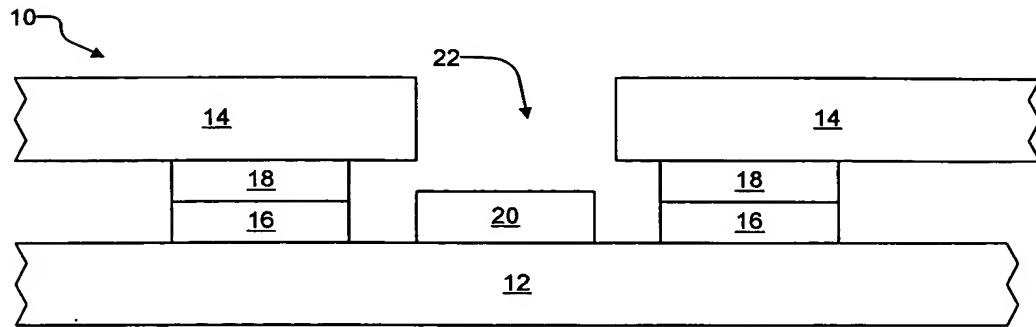


Fig. 1

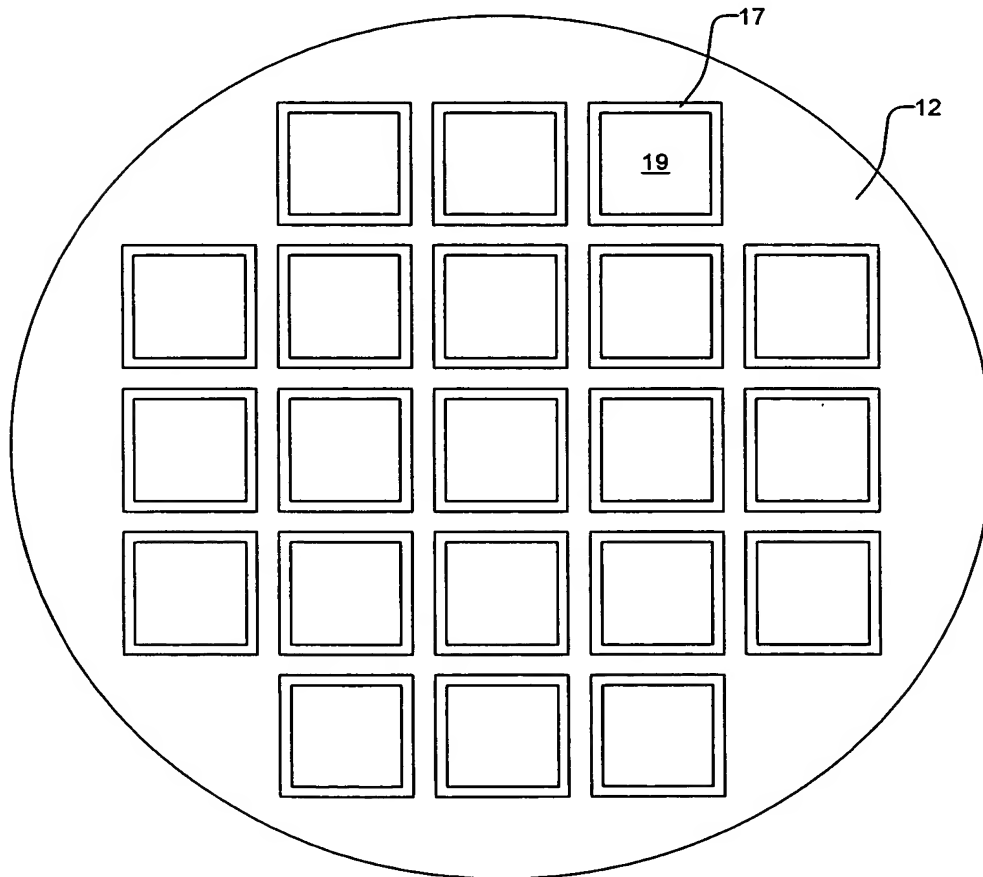


Fig. 1A

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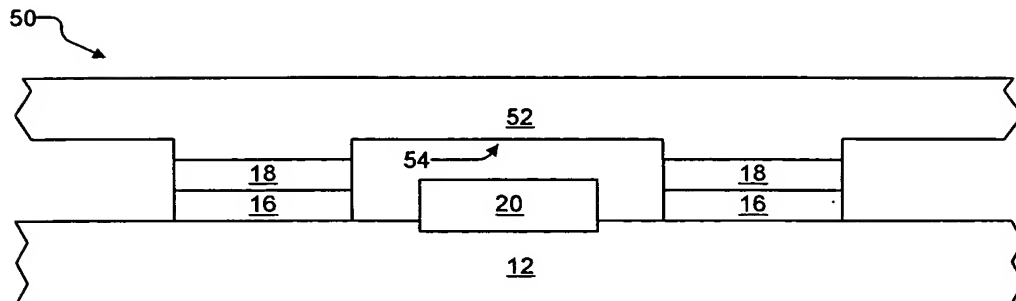


Fig. 2

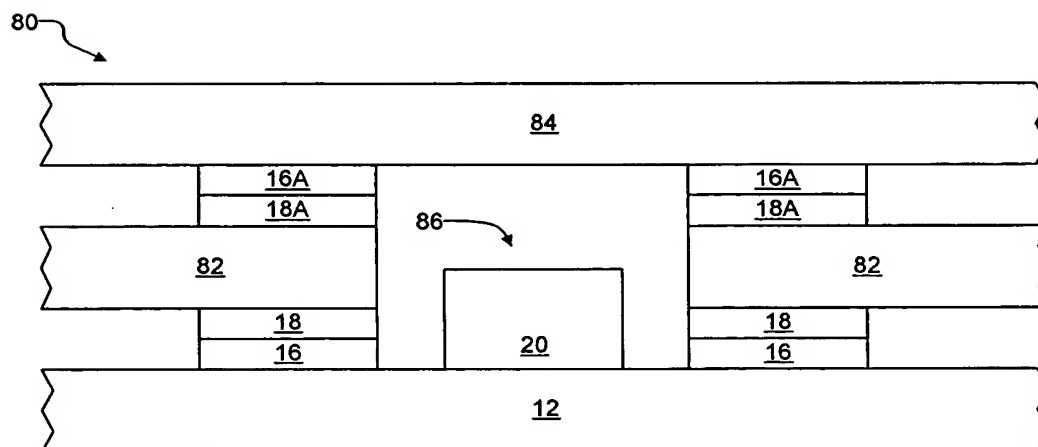


Fig. 3

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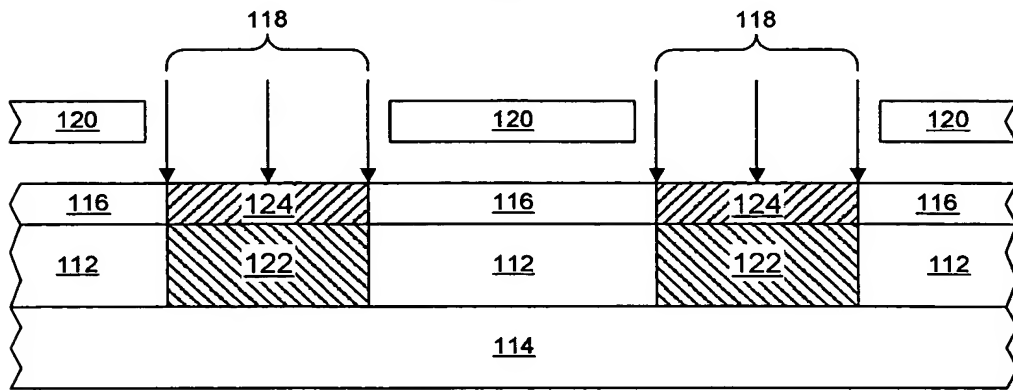


Fig. 4A

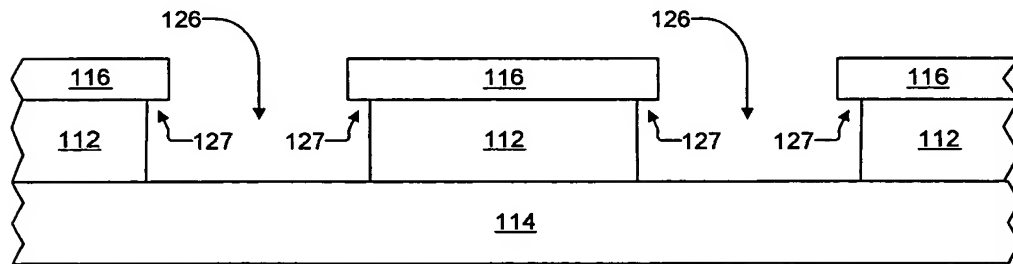


Fig. 4B

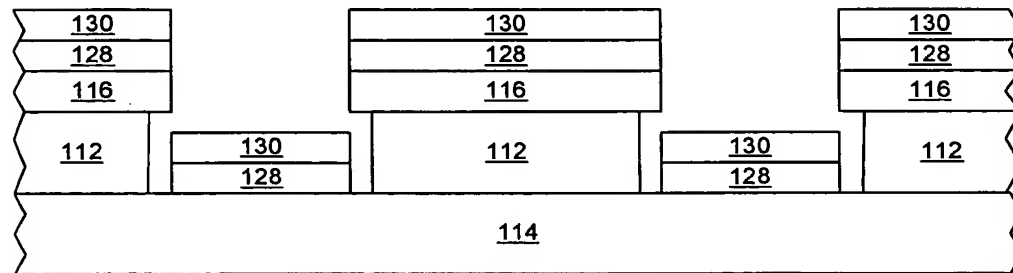


Fig. 4C

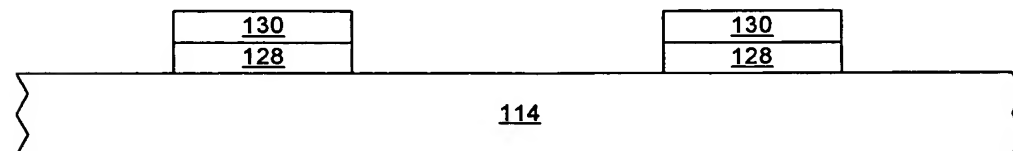


Fig. 4D

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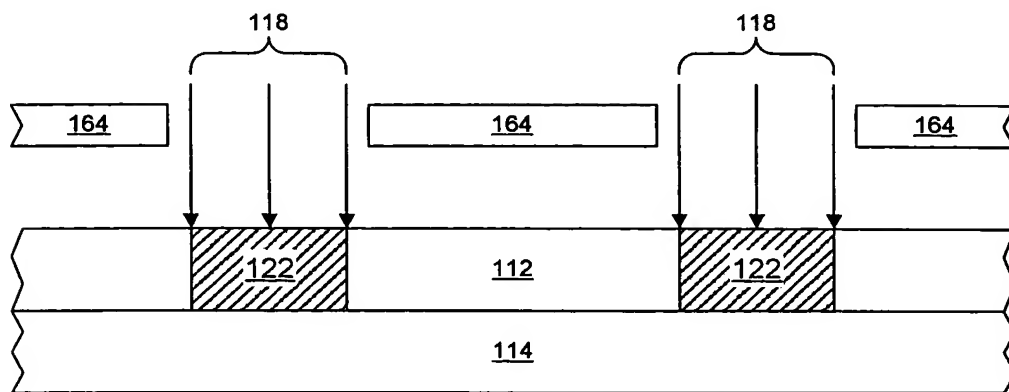


Fig. 5A

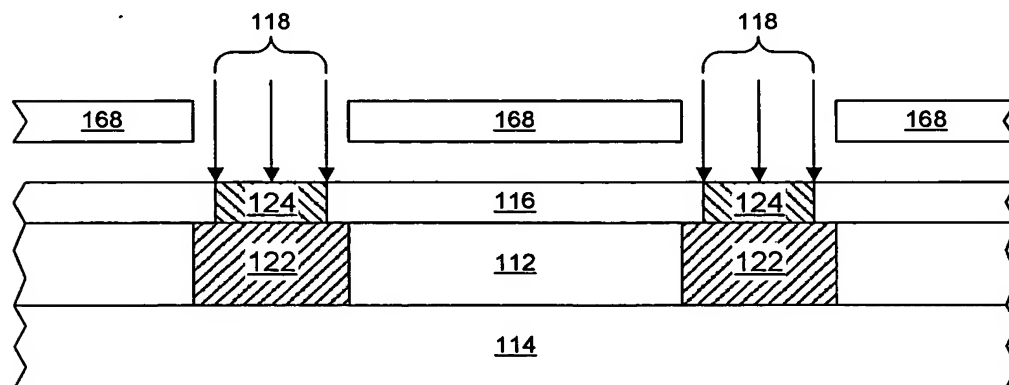


Fig. 5B

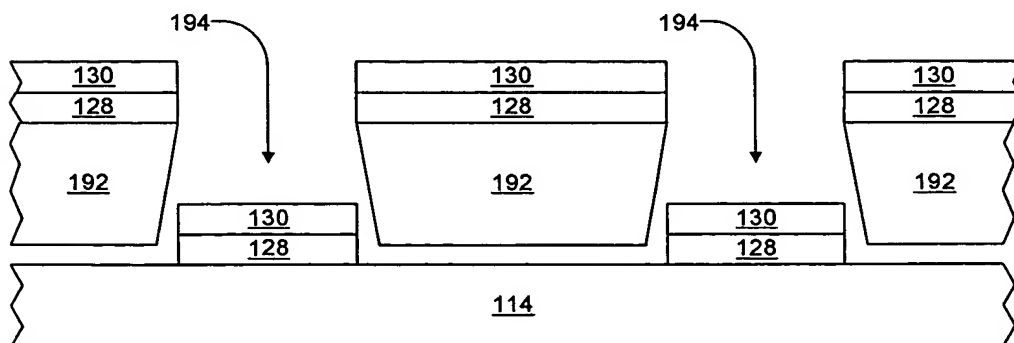


Fig. 6

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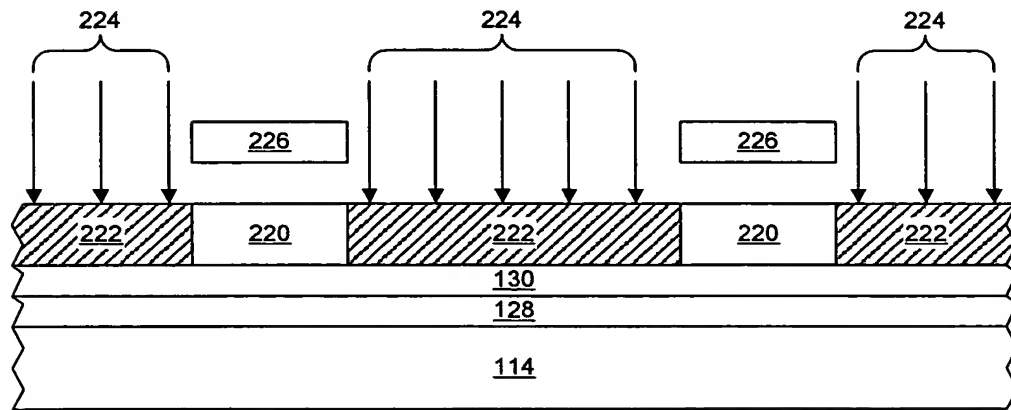


Fig. 7A

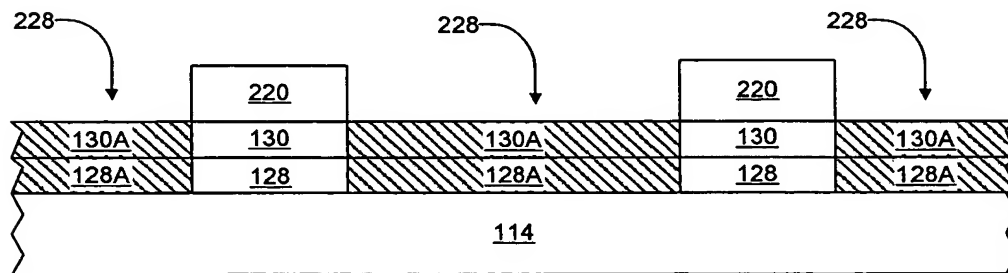


Fig. 7B

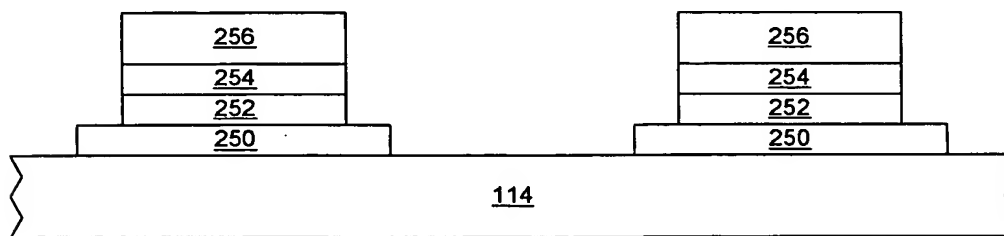


Fig. 8

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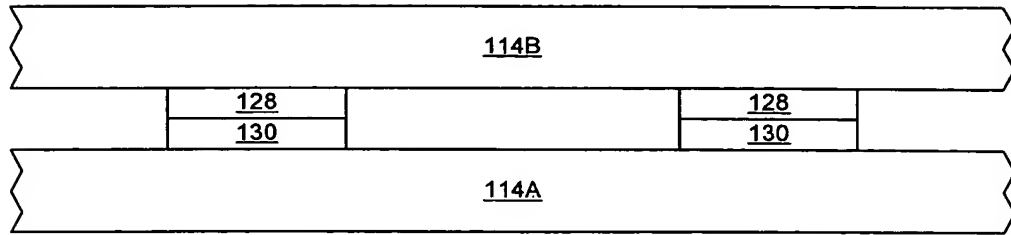


Fig. 9A

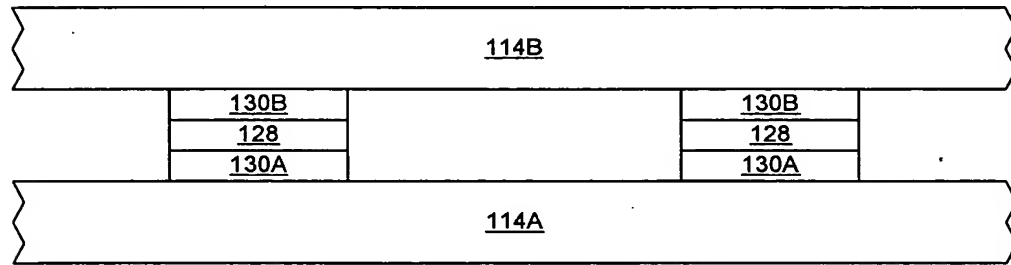


Fig. 9B